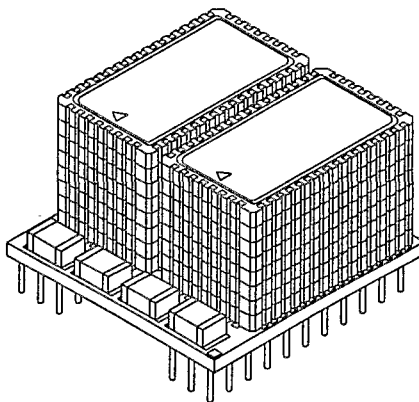


**ADVANCED INFORMATION**

**DESCRIPTION:**

The DPS512X32AV3 "VERSA-STACK" module is a revolutionary new high speed memory subsystem using Dense-Pac Microsystems' ceramic Stackable Leadless Chip Carriers (SLCC) mounted on a cofired ceramic substrate. It offers 16 Megabits of CMOS static RAM in a package envelope of 1.09 x 1.09 x 0.72 inches.

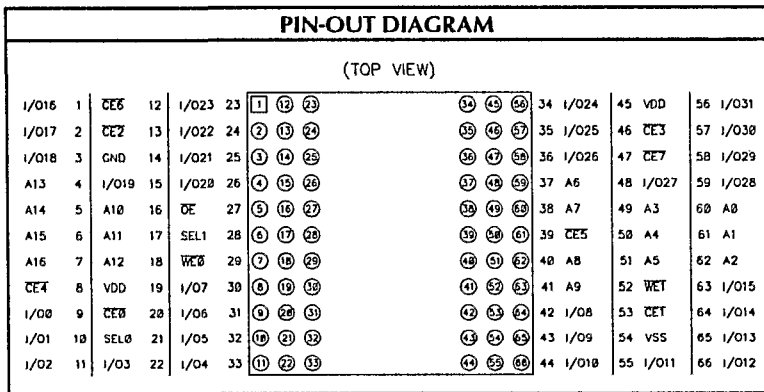
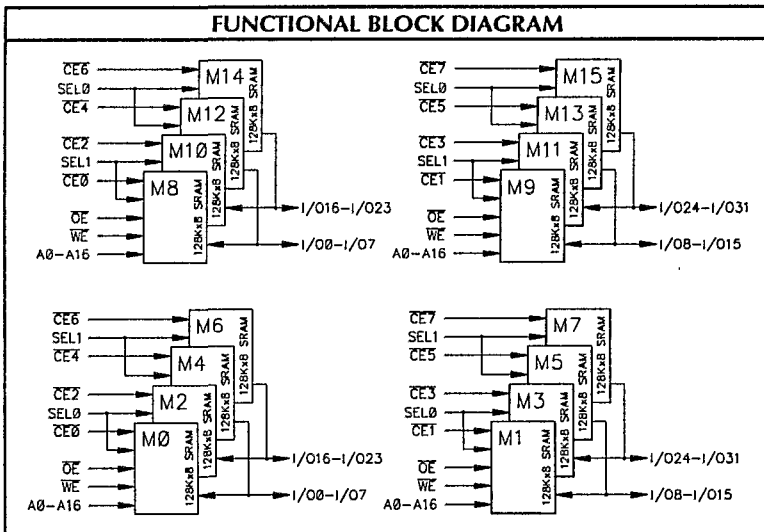
The DPS512X32AV3 contains sixteen individual 128K x 8 SRAMs, packaged in their own hermetically sealed SLCCs making the module suitable for commercial, industrial and military applications. By using SLCCs, the "Versa-Stack" family of modules offers a higher board density of memory than available with conventional through-hole, surface mount, module, or hybrid techniques.



**FEATURES:**

- Organizations Available:  
512K x 32, 1024K x 16,  
or 2048K x 8
- Access Times:  
35\*, 45, 55, 70ns
- Low Power Dissipation:  
800µW (typ.) Standby  
1760mW (typ.) Operating
- Fully Static Operation - No clock  
or refresh required
- Low Data Retention Current:  
80µA typ. (2.0V)
- Single +5V Power Supply,  
±10% Tolerance
- TTL Compatible
- Common Data Inputs and  
Outputs
- 66-Pin PGA "VERSA-STACK"  
Package
- Commercial only.

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**PIN NAMES**

A0 - A16	Address Inputs
I/00 - I/031	Data Input/Output
CE0 - CE7	Low Chip Enables
SEL0, SEL1	High Chip Enables
WE	Write Enable
OE	Output Enable
VDD	Power (+5V)
VSS	Ground

DETAILED INFORMATION WAS NOT AVAILABLE  
AT THE PUBLICATION DATE.

CONTACT YOUR LOCAL SALES OFFICE  
FOR MORE DETAILED INFORMATION.

***Dense-Pac Microsystems, Inc.***

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